

**For Immediate Release**  
**See StratEdge at MTT-S 2007 Booth 543**

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**[Photo and measured data available at: http://theedge.cts.com/580471\\_580468.jpg](http://theedge.cts.com/580471_580468.jpg)**

**StratEdge Announces New Package Line to Support Power Applications**  
*Packages utilize beryllium oxide for use with power semiconductor devices*

**San Diego, Calif – April 16, 2007** – StratEdge, leader in the design and production of semiconductor packages for microwave, millimeter wave, and high speed digital devices, announced the release of its Power Package Series at the RF & Hyper Trade Show in Paris, France and will feature them in the United States at the MTT-S show in Honolulu, Hawaii on June 5-7 at booth 543. The new line of packages can be used in silicon, silicon carbide, gallium nitride, and other applications for power integrated circuits. Thermally conductive beryllium oxide (BeO) ceramic give the packages excellent thermal properties.

The Power Package Series comes in industry-standard outlines. Both hermetic and non-hermetic packages are available. These packages provide superior electrical performance and incorporate copper composite bases for enhanced thermal dissipation. Hermetic packages in this series are sealed with metal or ceramic lids that have gold-tin solder preforms. The non-hermetic version is sealed with cup-shaped ceramic or liquid crystal polymer lids with B-stage epoxy preforms.

“The quality of a package’s construction is directly proportional to the performance of the chip,” explained StratEdge senior applications engineer Jerry Carter, who made the announcement at the RF & Hyper Trade Show last month. “Design engineers know that if they use StratEdge packages, their chips will perform to the specifications of their designs. We are used to creating packages that can handle high frequencies and high heat. For our Power Package Series, we came up with a new hermetic package construction with improved reliability that still fits the industry-standard outlines.”

“StratEdge has specialized in the design, manufacture, and assembly of high performance semiconductor packages for almost 20 years,” said StratEdge president Tim Going. “Several of our customers needed power packages and couldn’t find the quality, reliability, and customized

services available at StratEdge. The way the packages are constructed is nearly identical to some of our existing package families. The manufacturing technology is very mature and stable. We are quite excited about offering this new product line.”

### **About StratEdge**

StratEdge, founded in 1992, designs, manufactures, and provides test and assembly services for a complete line of high performance semiconductor packages operating from DC to 50+ GHz for the high speed digital (OC-48, OC-192, OC-768), mixed signal, broadband wireless, satellite, point-to-point/multipoint, VSAT, and test and measurement industries, as well as aerospace stripline filters. StratEdge offers ceramic, low cost hermetic SMT, and metal packages. All packages are lead-free and meet RoHS and WEEE standards. For more information contact StratEdge at 858-560-6877, email: [info@stratedge.com](mailto:info@stratedge.com), or visit our website at [www.stratedge.com](http://www.stratedge.com).

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